

N-Channel 100-V (D-S) MOSFET

PRODUCT SUMMARY

V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D (A) ^a	Q_g (Typ)
100	0.075 at $V_{GS} = 10$ V	20	31 nC

FEATURES

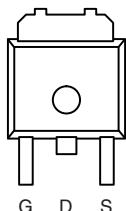
- TrenchFET® Power MOSFET
- 100 % UIS Tested



APPLICATIONS

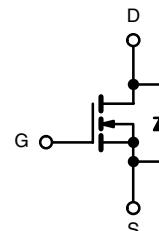
- Primary Side Switch

TO-252



Drain Connected to Tab

Top View



N-Channel MOSFET

Ordering Information: SUD35N10-26P-E3 (Lead (Pb)-free)

ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current ($T_J = 175$ °C)	I_D	20	A
		18	
		12 ^{b, c}	
		10 ^{b, c}	
Pulsed Drain Current	I_{DM}	40	
Continuous Source-Drain Diode Current	I_S	50 ^e	
		6.9 ^{b, c}	
Avalanche Current Pulse	I_{AS}	33	
Single Pulse Avalanche Energy	E_{AS}	55	
	P_D	63	
		48	
		8.3 ^{b, c}	
Maximum Power Dissipation		5.8 ^{b, c}	W
	T_J, T_{stg}	-55 to 175	

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{b, d}	R_{thJA}	15	18	°C/W
Maximum Junction-to-Case	R_{thJC}	1.5	1.8	

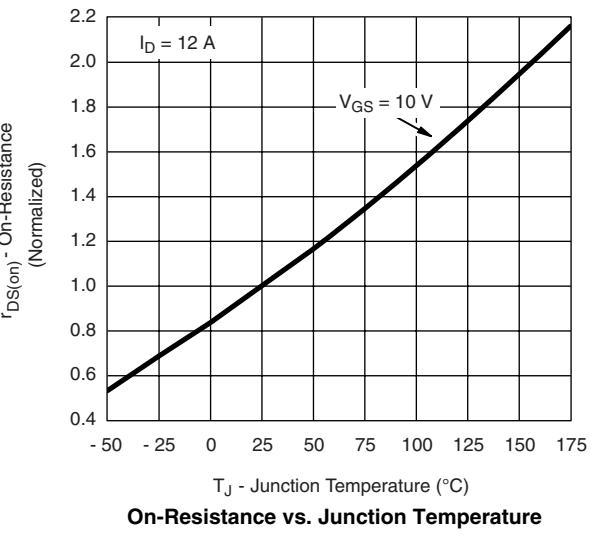
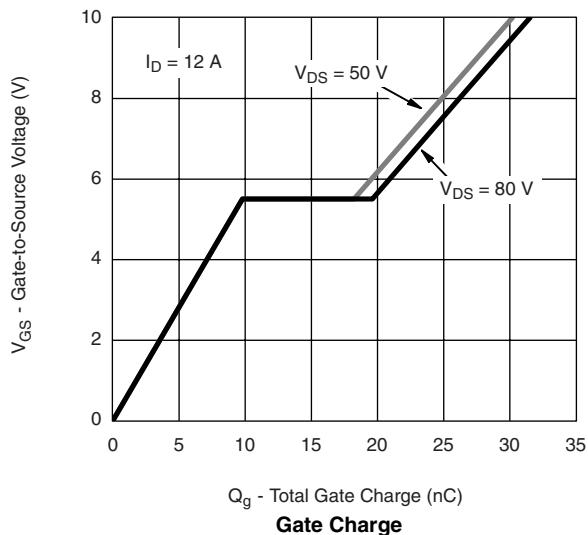
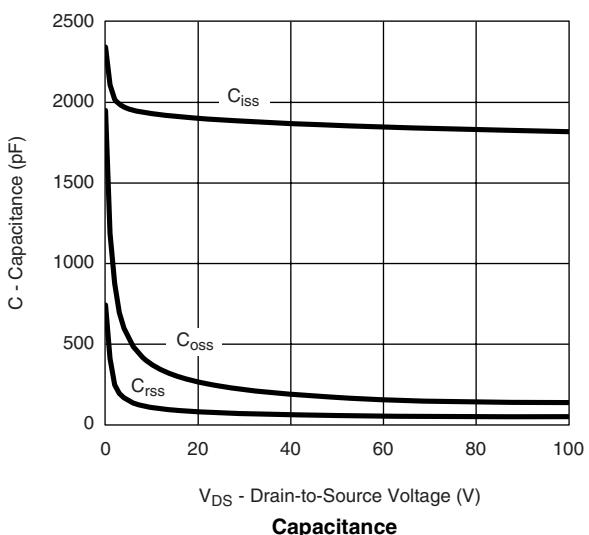
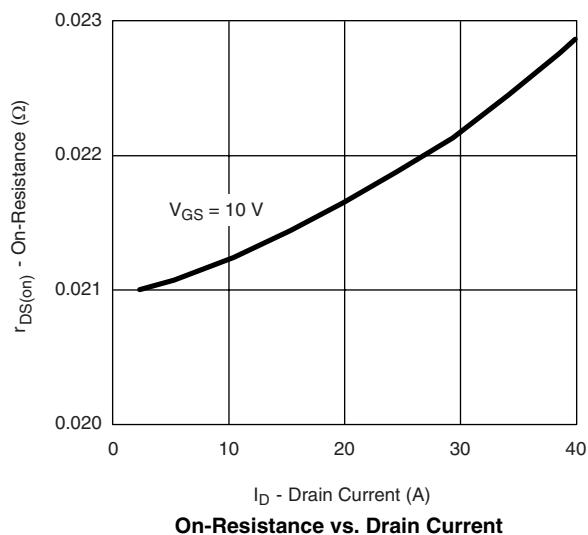
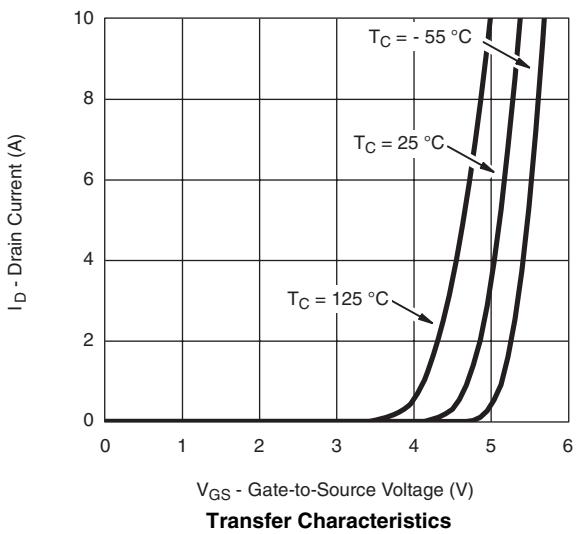
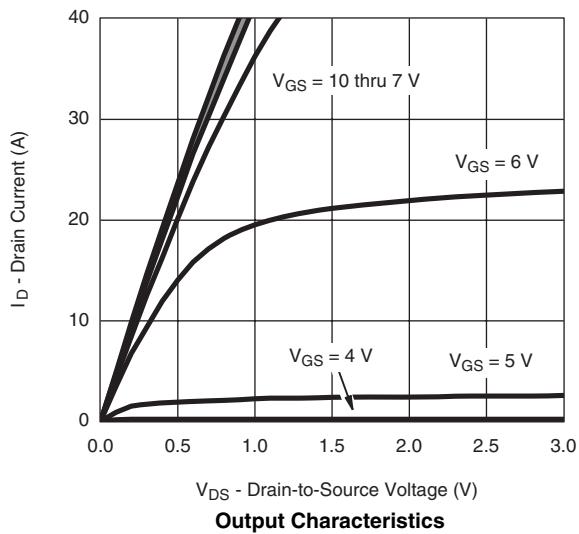
**SPECIFICATIONS** $T_J = 25^\circ\text{C}$, unless otherwise noted

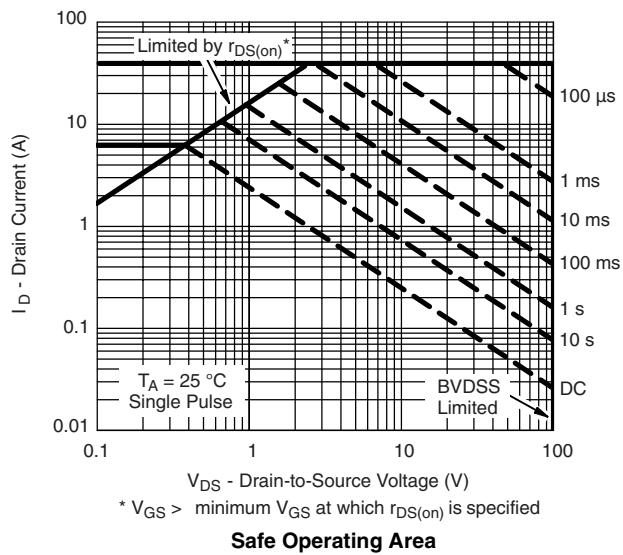
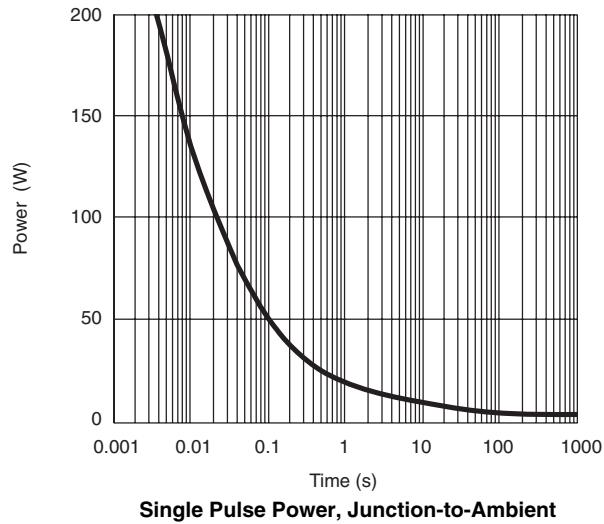
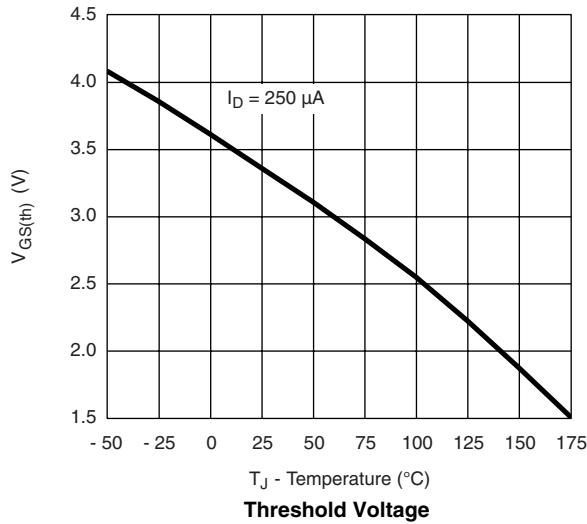
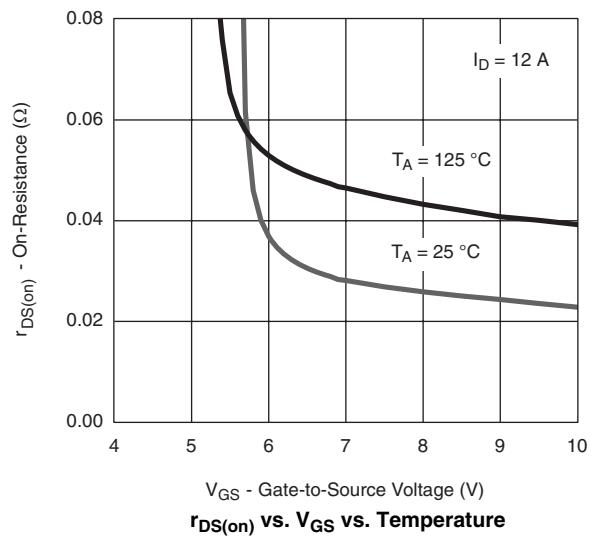
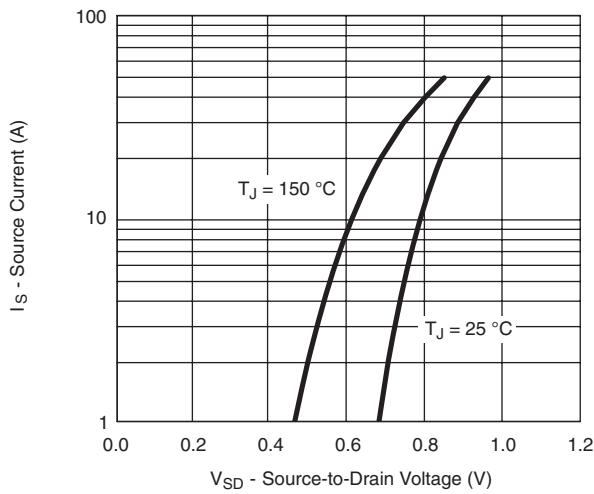
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = 250 \mu\text{A}$		165		$\text{mV}/^\circ\text{C}$
$V_{GS(\text{th})}$ Temperature Coefficient	$\Delta V_{GS(\text{th})}/T_J$			- 11		
Gate-Source Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	1.3		2.0	V
Gate-Source Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}$			1	μA
		$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55^\circ\text{C}$			10	
On-State Drain Current ^a	$I_{D(\text{on})}$	$V_{DS} \geq 5 \text{ V}, V_{GS} = 10 \text{ V}$	40			A
Drain-Source On-State Resistance ^a	$r_{DS(\text{on})}$	$V_{GS} = 10 \text{ V}, I_D = 12 \text{ A}$		0.078	0.090	Ω
Forward Transconductance ^a	g_{fs}	$V_{DS} = 15 \text{ V}, I_D = 12 \text{ A}$		25		S
Dynamic^b						
Input Capacitance	C_{iss}	$V_{DS} = 12 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		2000		pF
Output Capacitance	C_{oss}			180		
Reverse Transfer Capacitance	C_{rss}			60		
Total Gate Charge	Q_g	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 12 \text{ A}$		31	47	nC
Gate-Source Charge	Q_{gs}			10		
Gate-Drain Charge	Q_{gd}			9		
Gate Resistance	R_g	$f = 1 \text{ MHz}$		1.5		Ω
Turn-On Delay Time	$t_{d(\text{on})}$	$V_{DD} = 50 \text{ V}, R_L = 5 \Omega$ $I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		10	15	ns
Rise Time	t_r			10	15	
Turn-Off Delay Time	$t_{d(\text{off})}$			15	25	
Fall Time	t_f			10	15	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	$T_C = 25^\circ\text{C}$			50	A
Pulse Diode Forward Current ^a	I_{SM}				40	
Body Diode Voltage	V_{SD}	$I_S = 10 \text{ A}$		0.8	1.2	V
Body Diode Reverse Recovery Time	t_{rr}	$I_F = 10 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}, T_J = 25^\circ\text{C}$		50	75	ns
Body Diode Reverse Recovery Charge	Q_{rr}			100	150	
Reverse Recovery Fall Time	t_a			38		ns
Reverse Recovery Rise Time	t_b			12		

Notes:

a. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2 \%$.

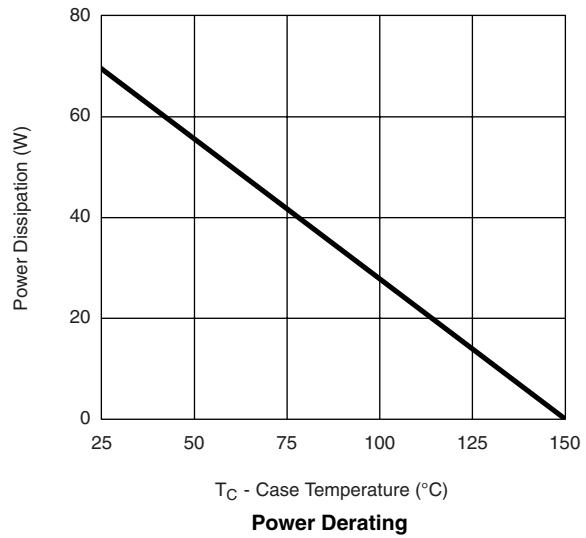
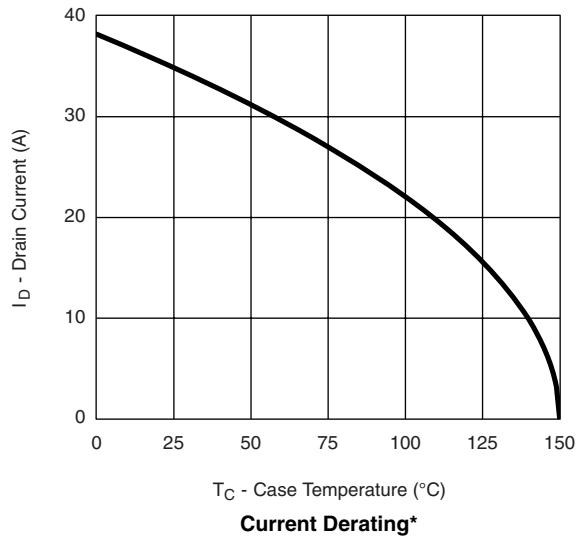
b. Guaranteed by design, not subject to production testing.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted


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